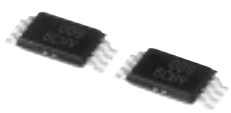


FY6BCH-02

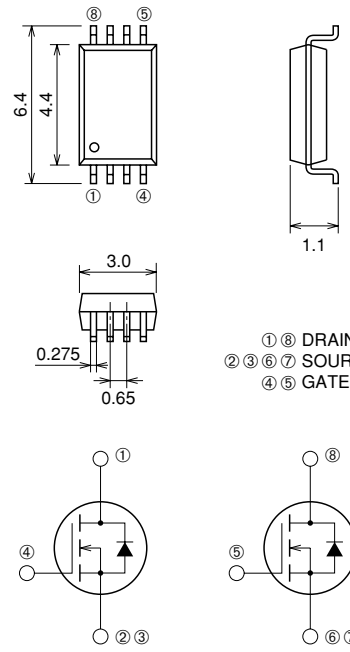
HIGH-SPEED SWITCHING USE

FY6BCH-02



- 2.5V DRIVE
- V_{DSS} 20V
- r_{DS (ON)} (MAX) 30mΩ
- I_D 6A

OUTLINE DRAWING Dimensions in mm



① ⑧ DRAIN
② ③ ⑥ ⑦ SOURCE
④ ⑤ GATE

TSSOP8

APPLICATION

Li-ion battery, DC-DC converter, etc.

MAXIMUM RATINGS (T_c = 25°C)

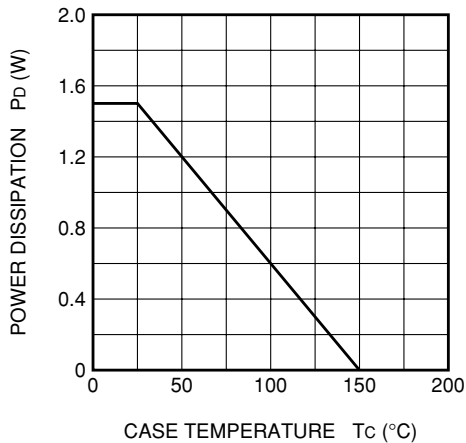
Symbol	Parameter	Conditions	Ratings	Unit
V _{DSS}	Drain-source voltage	V _{GS} = 0V	20	V
V _{GSS}	Gate-source voltage	V _{DS} = 0V	±10	V
I _D	Drain current		6	A
I _{DM}	Drain current (Pulsed)		42	A
I _{DA}	Avalanche drain current (Pulsed)	L = 10μH	6	A
I _S	Source current		1.5	A
I _{SM}	Source current (Pulsed)		6.0	A
P _D	Maximum power dissipation		1.5	W
T _{ch}	Channel temperature		-55 ~ +150	°C
T _{stg}	Storage temperature		-55 ~ +150	°C
—	Weight	Typical value	0.035	g

ELECTRICAL CHARACTERISTICS (T_{ch} = 25°C)

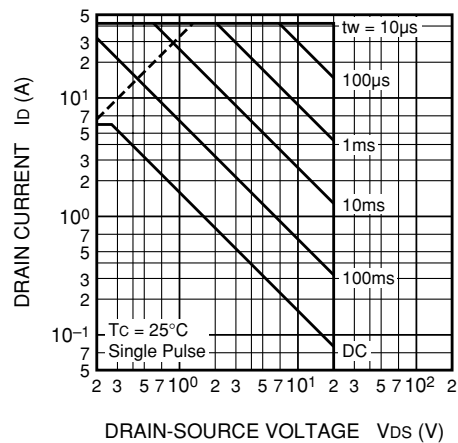
Symbol	Parameter	Test conditions	Limits			Unit
			Min.	Typ.	Max.	
V _{(BR)DSS}	Drain-source breakdown voltage	I _D = 1mA, V _{GS} = 0V	20	—	—	V
I _{GSS}	Gate-source leakage current	V _{GS} = ±10V, V _{DS} = 0V	—	—	±0.1	μA
I _{DSS}	Drain-source leakage current	V _{DS} = 20V, V _{GS} = 0V	—	—	0.1	mA
V _{GS(th)}	Gate-source threshold voltage	I _D = 1mA, V _{DS} = 10V	0.5	0.9	1.3	V
r _{DS(ON)}	Drain-source on-state resistance	I _D = 6A, V _{GS} = 4V	—	25	30	mΩ
r _{DS(ON)}	Drain-source on-state resistance	I _D = 3A, V _{GS} = 2.5V	—	32	40	mΩ
V _{DS(ON)}	Drain-source on-state voltage	I _D = 6A, V _{GS} = 4V	—	0.15	0.18	V
y _{fs}	Forward transfer admittance	I _D = 6A, V _{DS} = 10V	—	13.0	—	S
C _{iss}	Input capacitance	V _{DS} = 10V, V _{GS} = 0V, f = 1MHz	—	800	—	pF
C _{oss}	Output capacitance		—	280	—	pF
C _{rss}	Reverse transfer capacitance		—	200	—	pF
t _{d(on)}	Turn-on delay time	V _{DD} = 10V, I _D = 3A, V _{GS} = 4V, R _{GEN} = R _{GS} = 50Ω	—	20	—	ns
t _r	Rise time		—	55	—	ns
t _{d(off)}	Turn-off delay time		—	90	—	ns
t _f	Fall time		—	100	—	ns
V _{SD}	Source-drain voltage	I _S = 1.5A, V _{GS} = 0V	—	—	1.10	V
R _{th(ch-a)}	Thermal resistance	Channel to ambient	—	—	83.3	°C/W
t _{rr}	Reverse recovery time	I _S = 1.5A, di _s /dt = -50A/μs	—	50	—	ns

PERFORMANCE CURVES

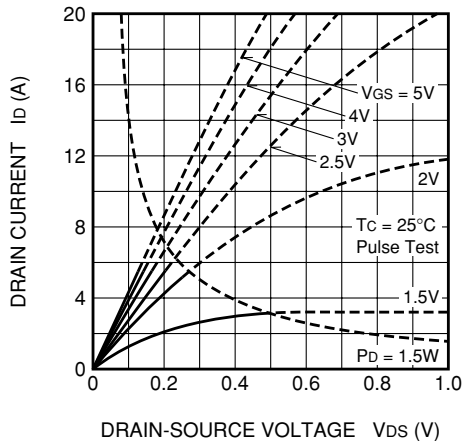
POWER DISSIPATION DERATING CURVE



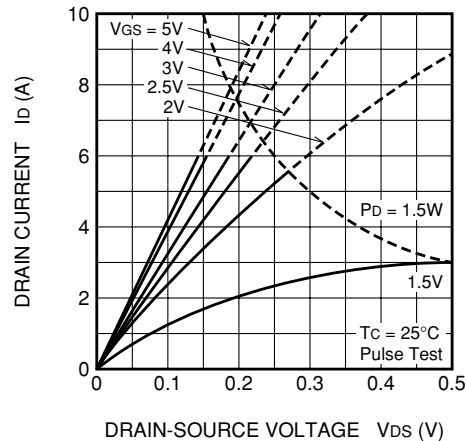
MAXIMUM SAFE OPERATING AREA



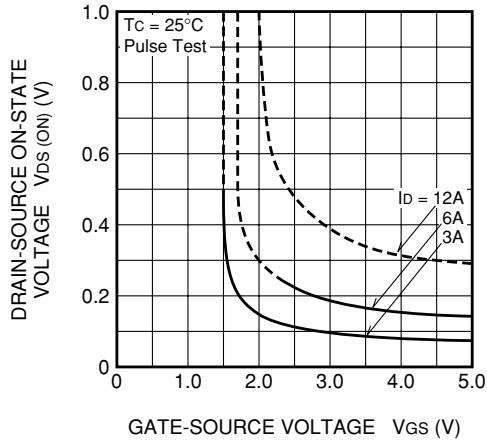
OUTPUT CHARACTERISTICS (TYPICAL)



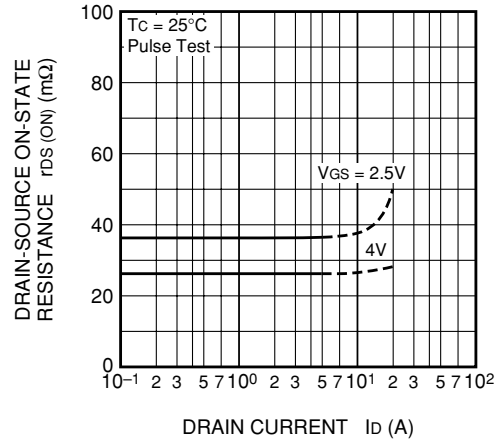
OUTPUT CHARACTERISTICS (TYPICAL)



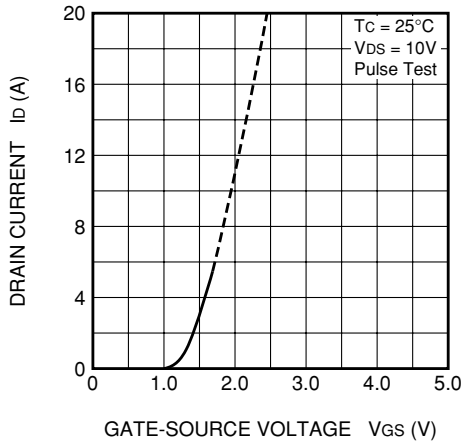
ON-STATE VOLTAGE VS. GATE-SOURCE VOLTAGE (TYPICAL)



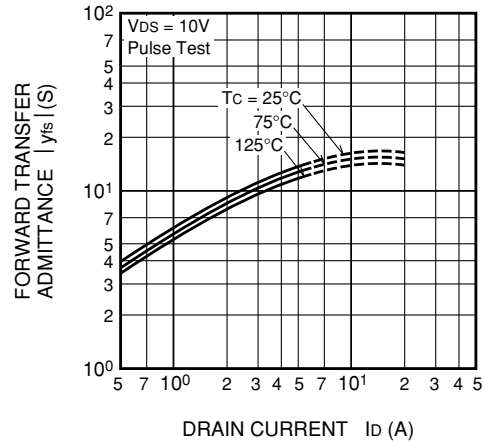
ON-STATE RESISTANCE VS. DRAIN CURRENT (TYPICAL)



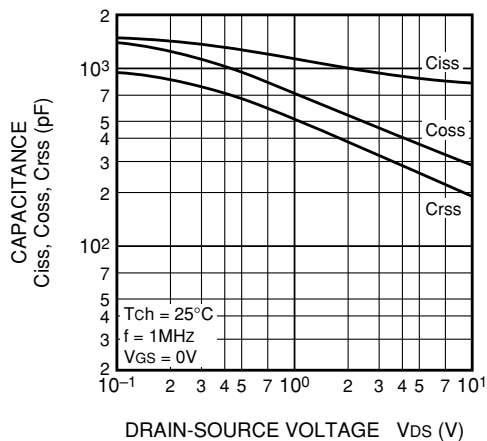
TRANSFER CHARACTERISTICS (TYPICAL)



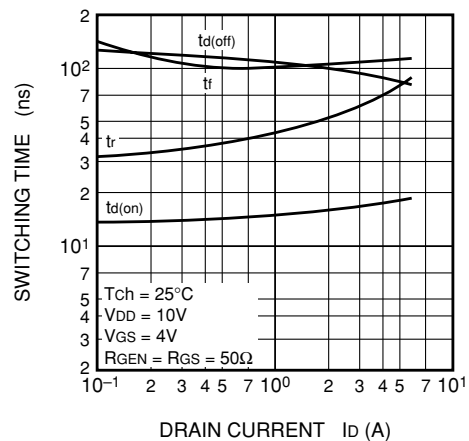
FORWARD TRANSFER ADMITTANCE VS. DRAIN CURRENT (TYPICAL)



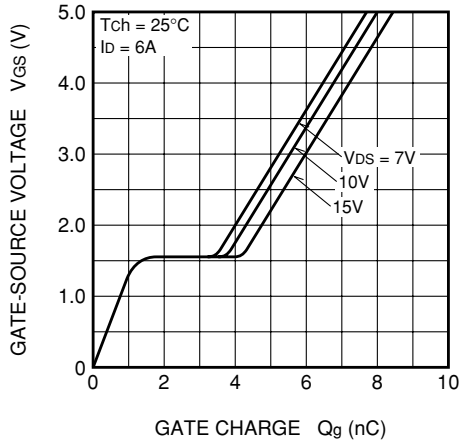
CAPACITANCE VS. DRAIN-SOURCE VOLTAGE (TYPICAL)



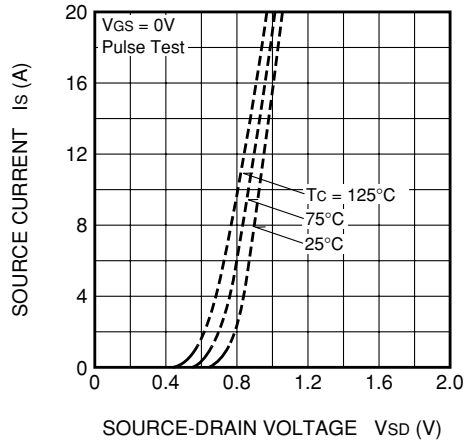
SWITCHING CHARACTERISTICS (TYPICAL)



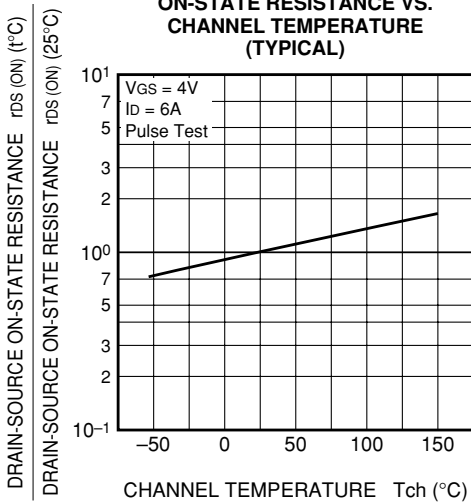
GATE-SOURCE VOLTAGE VS. GATE CHARGE (TYPICAL)



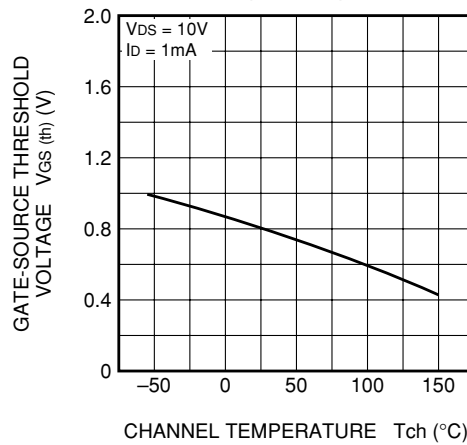
SOURCE-DRAIN DIODE FORWARD CHARACTERISTICS (TYPICAL)



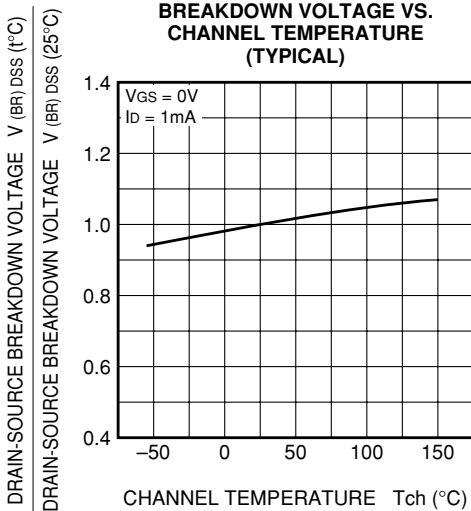
ON-STATE RESISTANCE VS. CHANNEL TEMPERATURE (TYPICAL)



THRESHOLD VOLTAGE VS. CHANNEL TEMPERATURE (TYPICAL)



BREAKDOWN VOLTAGE VS. CHANNEL TEMPERATURE (TYPICAL)



TRANSIENT THERMAL IMPEDANCE CHARACTERISTICS

